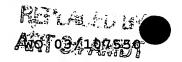


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## Patent Claims

- A method for making contact between at least one module for wire-free radio standards and at least one application, with
  - contact surfaces being provided on a side of the module which is intended to make contact with the application, and
- contact surfaces which can interact with the contact surfaces of the module being provided on a side of the application which is intended to make contact with the module, and
  - a connection being produced between the respective contact surfaces of the module and the application.
  - The method as claimed in claim 1, characterized
- in that a detachable connection is provided
  between the respective contact surfaces by means
  of a mechanical apparatus which allows the module
  to be replaced by pushing it in and out.
- The method as claimed in claim 1,
   characterized
   in that a firm connection is provided between the respective contact surfaces.
- 4. The method as claimed in claim:3,
  30 characterized
  in that the respective contact surfaces are soldered or pressed together.
- The method as claimed in one of the preceding
   claims,
   characterized





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in that the respective contact surfaces are arranged in the form of a grid.

The method as claimed in one of the preceding claims,

characterized

in that the contact surfaces are formed by a metallic coating with a low electrical and/or thermal resistance.

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7. A combination, having a module for wire-free radio standards and having an application, with the module having contact surfaces on a side which is intended to make contact with the application, and the application having contact surfaces on a side which is intended to make contact with the module, which latter contact surfaces can interact with the contact surfaces of the module and can make contact with them.

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8. The combination as claimed in claim 7, characterized in that the respective contact surfaces can be detachably connected to one another.

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9. The combination as claimed in claim 7, characterized in that the respective contact surfaces can be permanently connected to one another.

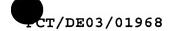
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10. The combination as claimed in claim 9, characterized in that the respective contact surfaces can be soldered to one another.

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11. The combination as claimed in one of claims 7 to 10,





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characterized

in that the respective contact surfaces are arranged in the form of a grid.

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## New Patent Claims

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- A method for making contact between at least one module for wire-free radio standards and at least one application, with
  - contact surfaces being provided on a side of the module which is intended to make contact with the application, and
  - contact surfaces which can interact with the contact surfaces of the module being provided on a side of the application which is intended to make contact with the module, and
  - produced connection being between the respective contact surfaces of the module and with least one of the application, at surfaces being formed by metallic contact a electrical and with low coating a resistance.
- A combination, having a module for wire-free radio 20 6. standards and having an application, with module having contact surfaces on a side which is intended to make contact with the application, and the application having contact surfaces on a side which is intended to make contact with the module, 25 which latter contact surfaces can interact with the contact surfaces of the module and can make contact with them, with at least one of the formed metallic surfaces being by а contact low electrical and thermal 30 with coating a resistance.